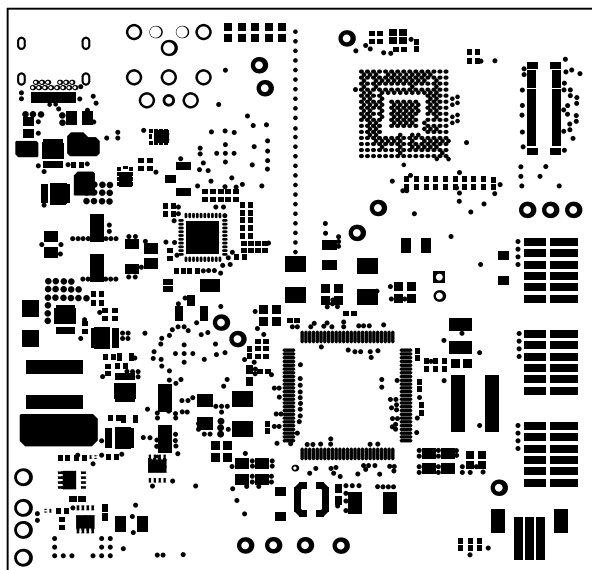
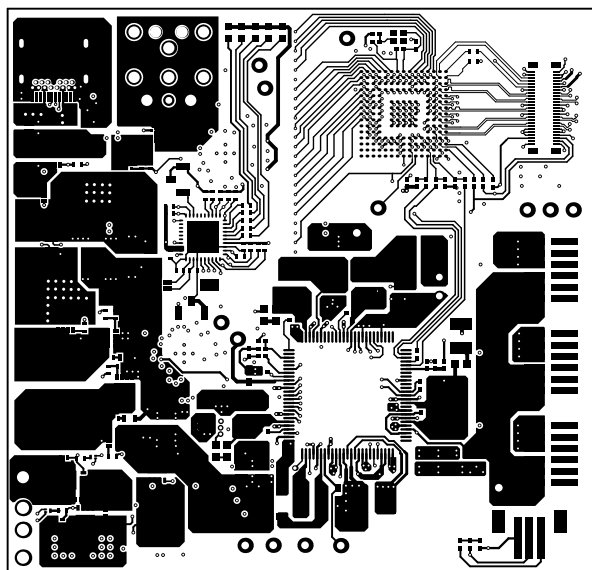


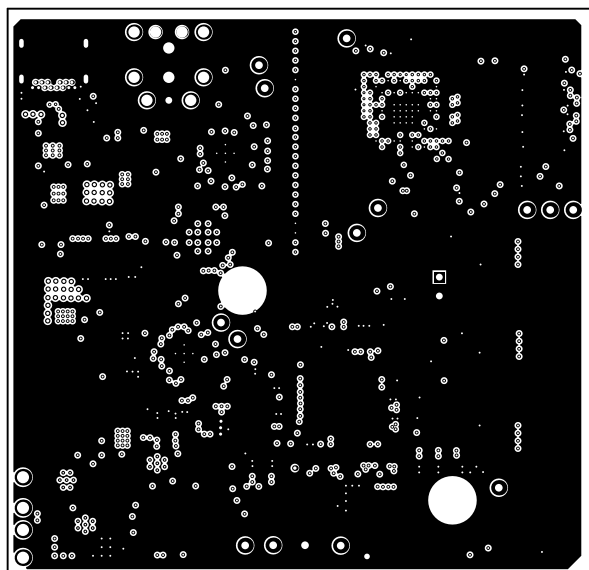
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40069	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP40069		
PLOT NAME = Top Overlay	GENERATED : 6/9/2017	4:56:54 PM	TEXAS INSTRUMENTS



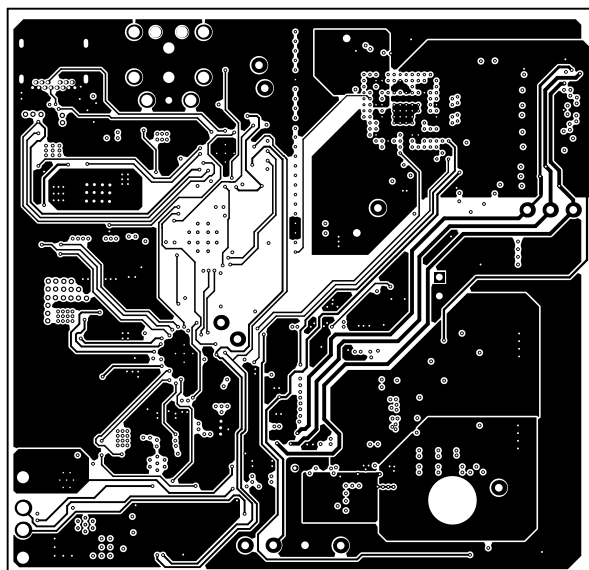
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40069	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP40069		
PLOT NAME = Top Solder Mask	GENERATED : 6/9/2017	4:56:55 PM	TEXAS INSTRUMENTS



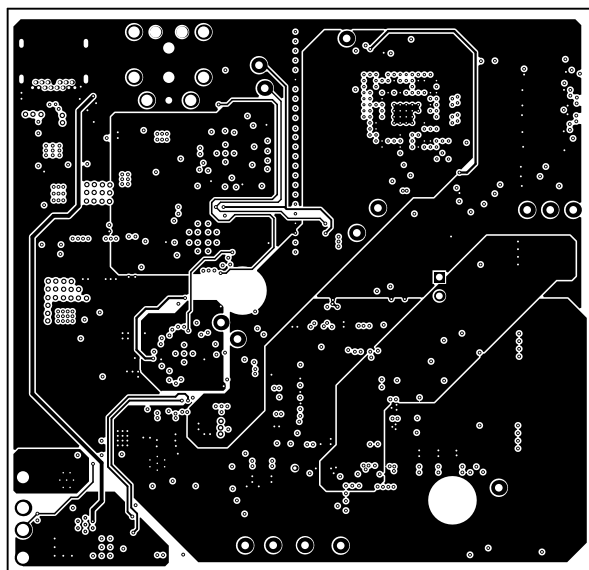
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40069	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP40069		
PLOT NAME = Top Layer	GENERATED : 6/9/2017	4:56:57 PM	TEXAS INSTRUMENTS



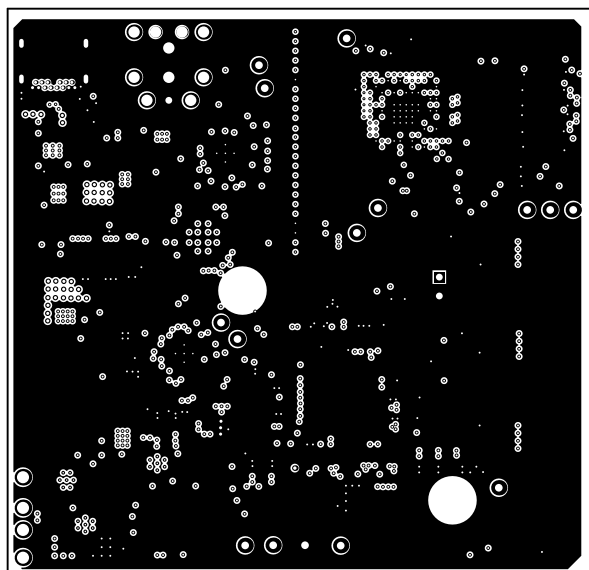
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40069	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP40069		
PLOT NAME = Signal Layer 1	GENERATED : 6/9/2017	4:56:58 PM	TEXAS INSTRUMENTS



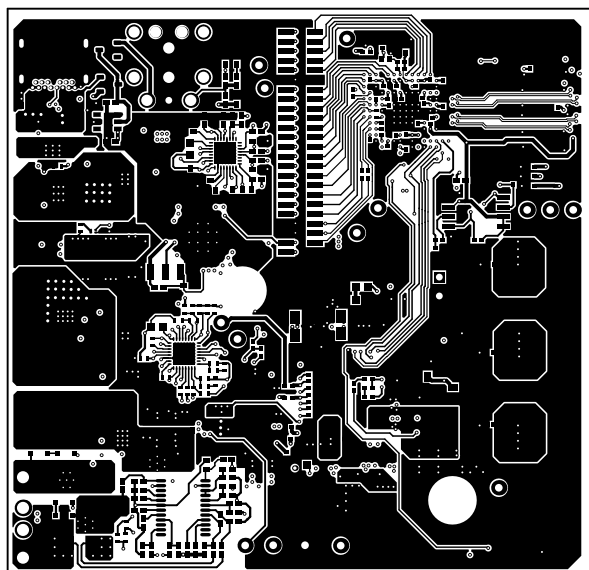
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40069	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP40069		
PLOT NAME = Signal Layer 2	GENERATED : 6/9/2017	4:57:00 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40069	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP40069		
PLOT NAME = Signal Layer 3	GENERATED : 6/9/2017	4:57:01 PM	TEXAS INSTRUMENTS

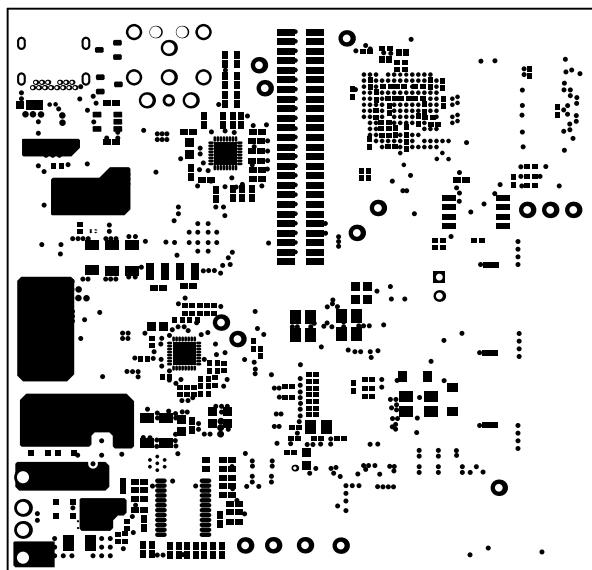


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40069	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP40069		
PLOT NAME = Signal Layer 4	GENERATED : 6/9/2017	4:57:03 PM	TEXAS INSTRUMENTS

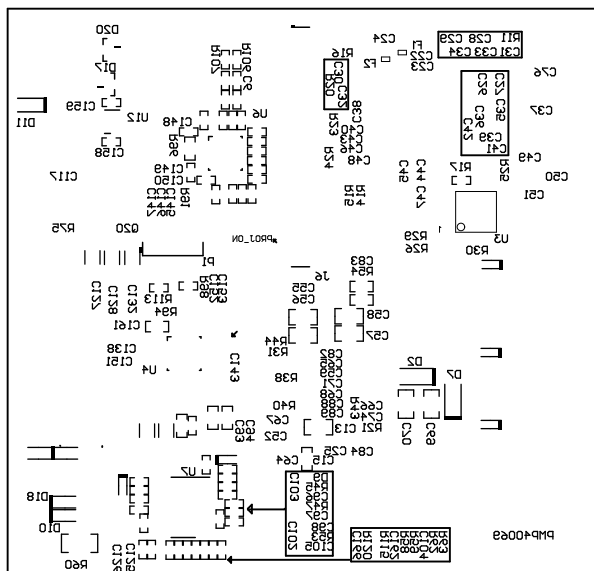


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40069	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP40069		
PLOT NAME = Bottom Layer	GENERATED : 6/9/2017	4:57:04 PM	TEXAS INSTRUMENTS

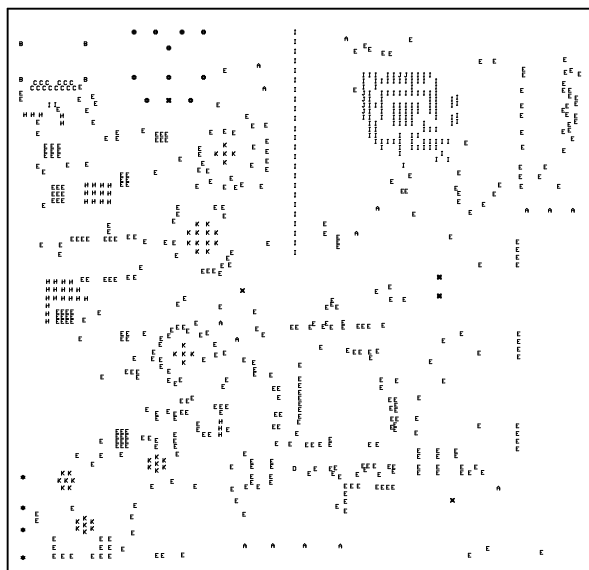




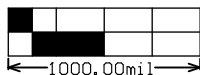
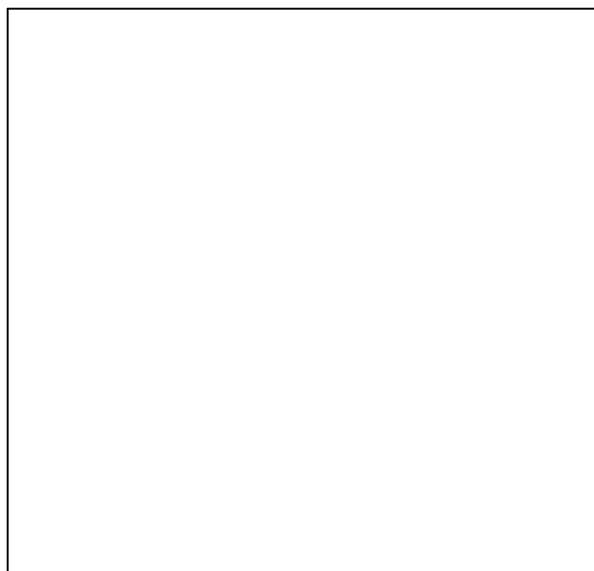
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40069	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP40069		
PLOT NAME = Bottom Solder Mask	GENERATED : 6/9/2017	4:57:06 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40069	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP40069		
PLOT NAME = Bottom Overlay	GENERATED : 6/9/2017	4:57:07 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40069	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP40069		
PLOT NAME = Drill Drawing	GENERATED : 6/9/2017	4:57:09 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40069	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP40069		
PLOT NAME = Board Dimensions	GENERATED : 6/9/2017	4:57:13 PM	TEXAS INSTRUMENTS

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